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Execution Date(s): May 27, 2011	Street Address:
Additional name(s) of conveying party(ies) attached? Yes X No	- , 1 120 Mail, Minato-Ru
3. Nature of Conveyance:	Tokyo 108-0075
x Assignment Merger	JAPAN
Security Agreement Change of Name	,
Government Interest Assignment	City:
Executive Order 9424. Confirmatory License	State:
Other	Country: Zip:
Other	Additional name(s) & address(es) Yes X No
4. Application or patent number(s):	
A. Palent Application No.(s)	This document is being filed together with a new application.
13/173,326	B. Patent No.(\$)
Additional numbers attached	Yes X No
Name and address to whom correspondence concerning document should be malled:	6. Total number of applications and patents involved:
lame: Dennis M. Smid, Esq.	Parents myorau.
LERNER, DAVID, LITTENBERG.	
KRUMHOLZ & MENTLIK, LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$_ 40.00
lemal Address; Atty. Dkt.; SONYJP 3.0-2560	Authorized to be charged by credit card
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ate: NJ Zip; 07090	a. Credit Card Last 4 Numbers
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nail Address: dsmid@ldlkm.com	Authorized User Name Dennis M. Smid, Esq.
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Dennis M. Smid, Esq 34,930	Total number of pages judyling cover
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PATENT REEL: 026553 FRAME: 0305

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Attorney Docket No. SONYJP 3.0-2560 SONY Ref. No.: \$11P1284US00

<u>ASSIGNMENT</u>

LDLKM

WHEREAS. I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) of certain new and useful improvements in

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address:

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries:

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, which may be granted for said invention, and in and to any and all Letters Patent of the United States, and countries foreign thereto, the Protection of Industrial Property. Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further continueration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 13/173,326 Filing Date: June 30, 2011 This assignment executed on the dates indicated below. TAKEHIRO SUGITA Name of first or sole inventor Execution date of U.S. Patent Application KANAGAWA JAPAN Residence of First or sole inventor Signature of first or sole inventor May 27, 2011 Date of this assignment Name of second inventor Execution date of U.S. Patent Application Residence of second inventor Signature of second inventor Date of this assignment Name of third inventor Execution date of U.S. Patent Application Residence of third inventor Signature of third inventor Date of this assignment

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PATENT REEL: 026553 FRAME: 0306